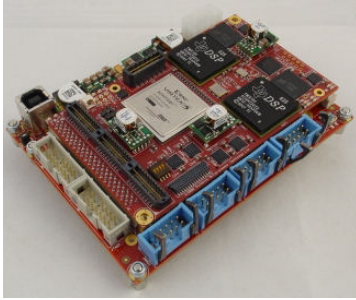


PRESS RELEASE

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SUNDANCE FEATURES NEW Texas
Instruments TMS320C6472
MULTICORE DSP IN ITS EVP6472
DEVELOPMENT PLATFORM



Sundance EVP6472 Embedded Development Platform Integrates Best Power Performance 3+ GHz Multicore DSP To Provide Cost- Performance Leadership for High-Performance Applications

London, UK – 3 November 2009 - Sundance, the leading supplier and manufacturer of advanced digital signal processing and reconfigurable FPGA systems, today extended its leadership in multiprocessor solutions through the introduction of its EVP6472 embedded development platform. The EVP6472 is the industry's first off-the-shelf multiprocessor, multicore solution that features dual Texas Instruments (TI) TMS320C6472 Digital Signal Processors (DSPs). Another industry first for the EVP6472 is design support from 3L's Diamond multiprocessor tool-suite. Diamond enables easy access to the on-board 12 C64x+™ cores and allows the designer to rapidly build, model, test and iterate different design architectures by moving tasks between the processor cores.

The EVP6472 is ideally suited to the development of high-performance applications such as high-end industrial, mission critical, test and measurement, communication, medical imaging, blade server and high-end image and video processing. It can be ordered online at www.evp6472.com or from your local Sundance Office. For a time limited period only, the EVP6472 is available at an introductory price of \$2000.00.

The six-core C6472 leads the industry in power consumption efficiency. The 500MHz C6472 is the best power performance multicore DSP with 0.15 mW/MIPS at 3 GHz performance. The 700MHz C6472 with a total 4.2 GHz performance and 4.8 MB on-chip L1/L2 memory is among the highest performance DSPs from TI. The C6472 architecture was designed to ensure a maximized subsystem performance on a chip. One of the advantages of this architecture is that in addition to dedicated Layer 1 (L1) and Layer 2 (L2) memory to each core, C6472 features 768KB shared L2 program/data memory and a shared memory controller to facilitate high efficient and flexible inter-DSP core communications. For further technical features, go to www.ti.com/c6472-pr-3p.

"Meeting the needs for today's leading-edge, high-performance applications, the C6472 supports applications that drive many channels, applications that demand maximum performance density and breakthrough applications for which designers must have access to sophisticated functions," said Daniel Chen, product marketing manager, High-Performance & Multicore Processing business at TI. "This level of capability combined with the Sundance multiprocessor format and modular flexibility will reduce the time-to-market for developers and OEMs building high-performance applications."

The EVP6472 is provided with a TIM carrier card and a modular plug-in that features dual C6472 multicore DSP, a Virtex5 FX30 FPGA with embedded PowerPC, 2 banks of DDR2 memory, Rocket Serial Link (RSL) connectors and a host USB 2.0 interface. The development platform is supported by TI's Code Composer Studio™ (CCS), and the 3L Diamond tool-suite that allows developers to separate the implementation of their application into: a software section based around communicating tasks; and, a hardware section built from processors joined by data-transfer links. Tasks can be placed on any of the twelve C64+ cores and the Diamond API allows the efficient exchange of data between tasks. Diamond uses its built-in device drivers to support uniform

communication, automatically using the shared memory between tasks and a virtual channel system is also available for deadlock-free data routing.

"This product announcement is another landmark for Sundance and for our customers, and it reflects the strength of the relationship we have developed with TI over many years," said Flemming Christensen, managing director of Sundance Multiprocessor Technology Ltd. said, "By coupling the cost performance advantages of the C6472 with a modular multiprocessing solution, we can deliver maximum development flexibility and the highest available performance/density ratio to application developers."

The EVP6472 is available for order with shipping in December 2009. For a time limited period pricing starts at \$2000.00. For more info. email EVP6472@sundance.com visit www.evp6472.com, or contact your local Sundance Office.

About Sundance

Sundance designs, develops, manufactures and markets internationally high performance signal processing and reconfigurable systems for original equipment manufacturers in the wireless and signal processing markets. Leveraging its multiprocessor expertise and experience, Sundance provides OEM with modular DSP and FPGA-based systems as well as data acquisition, I/O, communication and interconnectivity products that are essential to multiprocessor systems where scalability and performance are essential. With over fifty different modules and carriers for PCI, cPCI VME and Stand Alone platforms, Sundance is a solution provider to semiconductor, pharmaceutical and factory automation industries. Sundance, founded in 1989 by the current directors, is a member of the TI Third Party Program, Xilinx Alliance Partner and MathWorks' Connection programs. For more information visit www.sundance.com.

About the Texas Instruments Developer Network

Sundance is a member of the TI Developer Network, a community of respected, well-established companies offering products and services based on TI analog and digital technology. The Network provides a broad range of end-equipment solutions, embedded software, engineering services and development tools that help customers accelerate innovation to make the world smarter, healthier, safer, greener and more fun.

Trademarks

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